

MOSFETs Silicon N-Channel MOS (U-MOSVII-H)

SSM6N7002KFU

1. Applications

· High-Speed Switching

2. Features

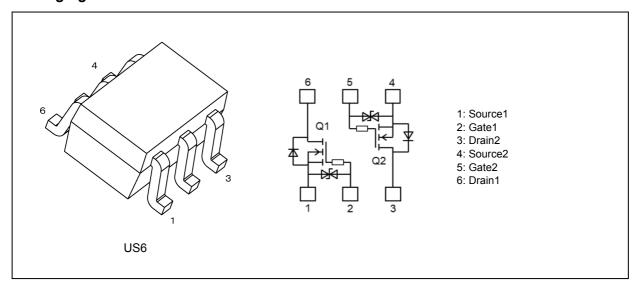
- (1) AEC-Q101 qualified (Please see the orderable part number list)
- (2) Low drain-source on-resistance

: $R_{DS(ON)} = 1.05 \Omega$ (typ.) (@ $V_{GS} = 10 \text{ V}$)

 $R_{\rm DS(ON)} = 1.15~\Omega~{\rm (typ.)}~(@V_{\rm GS} = 5.0~{\rm V})$

 $R_{\mathrm{DS(ON)}} = 1.2~\Omega~\mathrm{(typ.)}~(@V_{\mathrm{GS}} = 4.5~\mathrm{V})$

3. Packaging and Internal Circuit



4. Orderable part number

Orderable part number	AEC-Q101				
SSM6N7002KFU,LF	— General Use				
SSM6N7002KFU,LXG	YES	(Note 1)	Unintended Use (Note 1)		
SSM6N7002KFU,LXH	YES		Automotive Use		

Note 1: For more information, please contact our sales or use the inquiry form on our website.

Start of commercial production



5. Absolute Maximum Ratings (Note) (Unless otherwise specified, Ta = 25 °C)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	60	V
Gate-source voltage		V_{GSS}	±20	
Drain current (DC)	(Note 1), (Note 2)	I_D	300	mA
Drain current (pulsed)	(Note 1), (Note 3)	I _{DP}	1200	
Power dissipation	(Note 2), (Note 4)	P_D	500	mW
Power dissipation	(Note 4), (Note 5)		285	
Channel temperature		T _{ch}	150	°C
Storage temperature		T _{stg}	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Ensure that the channel temperature does not exceed 150 °C.

Note 2: T_{sp} = 25 °C

Note 3: Repetitive rating; pulse width limited by maximum channel temperature. pulse width \leq 10 $\mu s,$ Duty 1 %

Note 4: Total rating

Note 5: Device mounted on a 25.4 mm × 25.4 mm × 1.6 mm FR-4 glass epoxy board (Cu pad: 645 mm²)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

Note: The MOSFETs in this device are sensitive to electrostatic discharge. When handling this device, the worktables, operators, soldering irons and other objects should be protected against anti-static discharge.

Note: The channel-to-ambient thermal resistance, R_{th(ch-a)}, and the drain power dissipation, P_D, vary according to the board material, board area, board thickness and pad area. When using this device, be sure to take heat dissipation fully into account.



6. Electrical Characteristics

6.1. Static Characteristics (Unless otherwise specified, T_a = 25 °C)

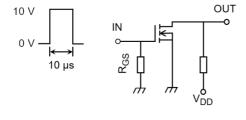
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	1		±10	μА
Drain cut-off current		I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V			1	
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = 250 \mu A, V_{GS} = 0 V$	60			V
Gate threshold voltage		V_{th}	$I_D = 250 \mu A, V_{DS} = V_{GS}$	1.1		2.1	
Drain-source on-resistance	(Note 1)	R _{DS(ON)}	I _D = 100 mA, V _{GS} = 10 V		1.05	1.5	Ω
			I _D = 100 mA, V _{GS} = 5.0 V	_	1.15	1.65	
			I _D = 100 mA, V _{GS} = 4.5 V	_	1.2	1.75	
Forward transfer admittance	(Note 1)	Y _{fs}	V _{DS} = 10 V, I _D = 200 mA		1.0	_	S

Note 1: Pulse measurement.

6.2. Dynamic Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V},$	_	26	40	pF
Reverse transfer capacitance	C _{rss}	f = 1 MHz	_	1.3	_	
Output capacitance	C _{oss}		_	5.5	_	
Switching time (rise time)	t _r	V _{DD} = 30 V, I _D = 200 mA	_	3.6	_	ns
Switching time (turn-on delay time)	t _{d(on)}	V_{GS} = 0 to 10 V, R_{GS} = 50 Ω Duty ≤ 1%, V_{IN} : t_r , t_f < 5 ns,	_	5.5	11	
Switching time (fall time)	t _f	Common source,	_	17	_	
Switching time (turn-off delay time)	t _{d(off)}	See Chapter 6.3.	_	38	90	

6.3. Switching Time Test Circuit



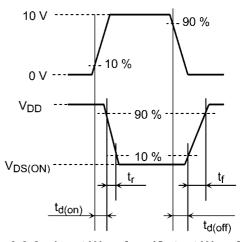


Fig. 6.3.1 Switching Time Test Circuit

Fig. 6.3.2 Input Waveform/Output Waveform

Rev.7.0

6.4. Gate Charge Characteristics (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	V_{DD} = 30 V, V_{GS} = 4.5 V,	_	0.39	0.6	nC
Gate-source charge	Q _{gs}	$I_D = 200 \text{ mA}$	_	0.2		
Gate-drain charge	Q _{gd}		_	0.11		

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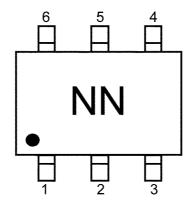


6.5. Source-Drain Characteristics (Unless otherwise specified, Ta = 25 °C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Diode forward voltage	(Note 1)	V_{DSF}	I _{DR} = 115 mA, V _{GS} = 0 V	_	0.79	1.1	V

Note 1: Pulse measurement.

7. Marking





8. Characteristics Curves (Note)

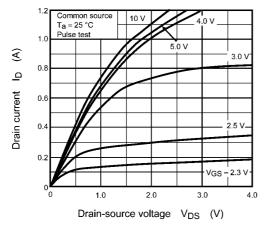


Fig. 8.1 I_D - V_{DS}

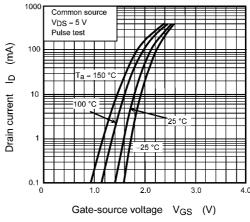


Fig. 8.2 I_D - V_{GS}

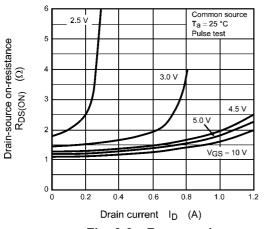


Fig. 8.3 R_{DS(ON)} - I_D

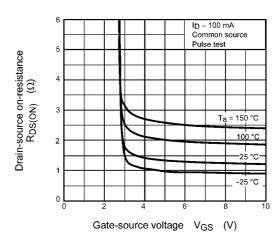


Fig. 8.4 R_{DS(ON)} - V_{GS}

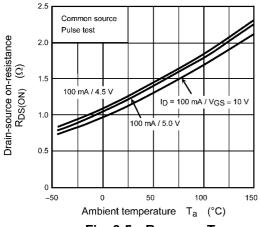


Fig. 8.5 $R_{DS(ON)}$ - T_a

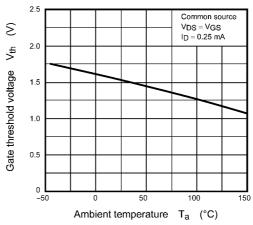
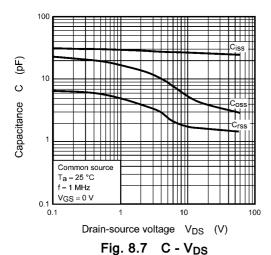
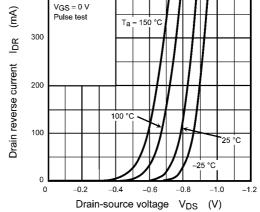


Fig. 8.6 V_{th} - T_a



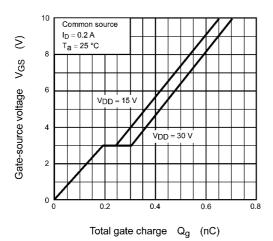




400

Common source





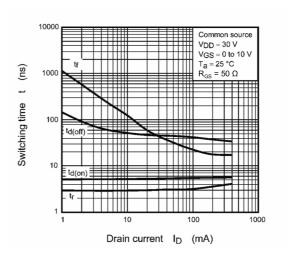
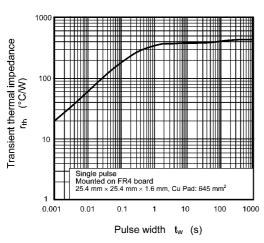


Fig. 8.9 Dynamic Input Characteristics

Fig. 8.10 t - I_D



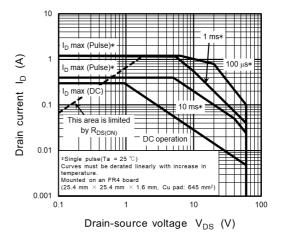


Fig. 8.11 rth - tw

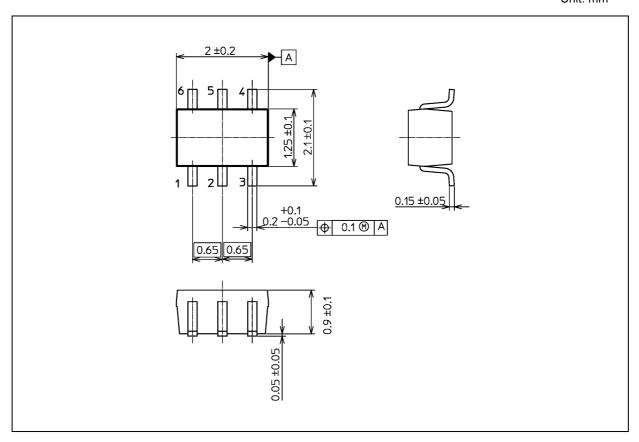
Fig. 8.12 Safe Operating Area

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



Package Dimensions

Unit: mm



Weight: 6.8 mg (typ.)

	Package Name(s)
JEDEC: SOT-363	
Nickname: US6	



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